



CALL FOR PAPERS

IMPORTANT DATES

March 15, 2021

Final Paper Submission Deadline

May 10, 2021

Notification of Acceptance

May 24, 2021

Final Manuscript Submission Deadline

May 31, 2021

Final Video Submission Deadline

June 10, 2021

Standard Registration Deadline

The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2021) will be held virtually.

IEEE FLEPS 2021 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible, Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic/Inorganic Electronic Sensors
- » Disposable/Reusable Sensors and Electronics
- » Emerging Materials for Flexible and Printable Systems
- » Printed Large-Area Sensors and Systems
- » Manufacturing Techniques
- » Flexible or Printed Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » High-throughput Printable Electronics
- » Emerging applications of Flexible Electronics inc. IoT, smart cities etc.
- » Hybrid Flexible Sensors and Electronics
- » Simulation and Modelling
- » Stretchable/Shrinkable Sensors and Electronics
- » Flexible/Printable Electronics in context with Circular Economy and green electronics
- » Soft/Smart Wearable and Implantable Sensing Systems

PUBLICATION OF PAPERS

Presented papers will be included in the Proceedings of IEEE FLEPS 2021 and in IEEE Xplore pending author requirements being met. Authors may submit an extended IEEE FLEPS 2021 papers to the Special Journal Issue in the IEEE Sensors Journal.

EXHIBITION & PATRON OPPORTUNITIES

The Conference exhibit area will provide your company or organization with the opportunity to inform and display your latest products, services, equipment, books, journals, and publications to attendees from around the world.

For further information, contact:

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Please visit: 2021.ieee-fleps.org



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